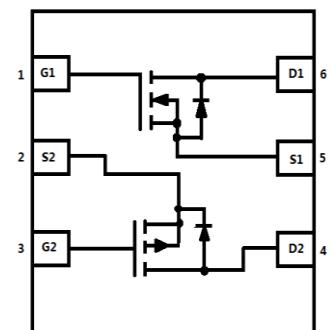
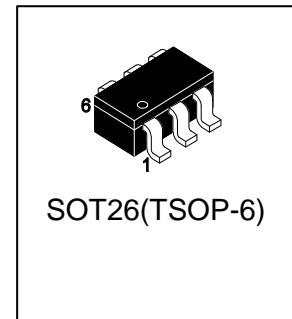


# S-LNP2601T1G

20 V Complementary Trench MOSFET

## 1. FEATURES

- N-Channel: VDS = 20V  
RDS(ON) ≤ 60mΩ, VGS@4.5V, IDS@1A  
RDS(ON) ≤ 75mΩ, VGS@2.5V, IDS@1A  
RDS(ON) ≤ 100mΩ, VGS@1.8V, IDS@1A
- P-Channel: VDS = -20V  
RDS(ON) ≤ 80mΩ, VGS@-4.5V, IDS@-1.0A  
RDS(ON) ≤ 95mΩ, VGS@-2.5V, IDS@-1.0A  
RDS(ON) ≤ 120mΩ, VGS@-1.8V, IDS@-1.0A
- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S-prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.



## 2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
S-LNP2601T1G	NP1	3000/Tape&Reel

## 3. Absolute Maximum Ratings (TA = 25 °C unless otherwise noted)

Parameter (N-Channel)	Symbol	Limits	Unit
Drain-Source Voltage	VDS	20	V
Gate-Source Voltage	VGS	±12	V
Drain Current-Continuous	ID	3	A
Drain Current-Pulsed(Note 1)	IDM	11	A

Parameter (P-Channel)	Symbol	Limits	Unit
Drain-Source Voltage	VDS	-20	V
Gate-Source Voltage	VGS	±8	V
Drain Current-Continuous	ID	-3.1	A
Drain Current-Pulsed(Note 1)	IDM	-9	A

## 4. THERMAL CHARACTERISTICS

Parameter	Symbol	Limits	Unit
Maximum Power Dissipation	PD	0.8	W
		0.6	
Thermal Resistance Junction-to-Ambient(Note 2)	R <sub>θJA</sub>	150	°C/W
Thermal Resistance Junction-to-Case	R <sub>θJC</sub>	100	°C/W
Operating Junction Temperature	T <sub>j</sub>	150	°C
Storage Temperature Range	T <sub>stg</sub>	-50~+150	°C

1.Repetitive Rating: Pulse width limited by the maximum junction temperature

2. 1-in<sup>2</sup> 2oz Cu PCB board

## 5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

### N-Channel

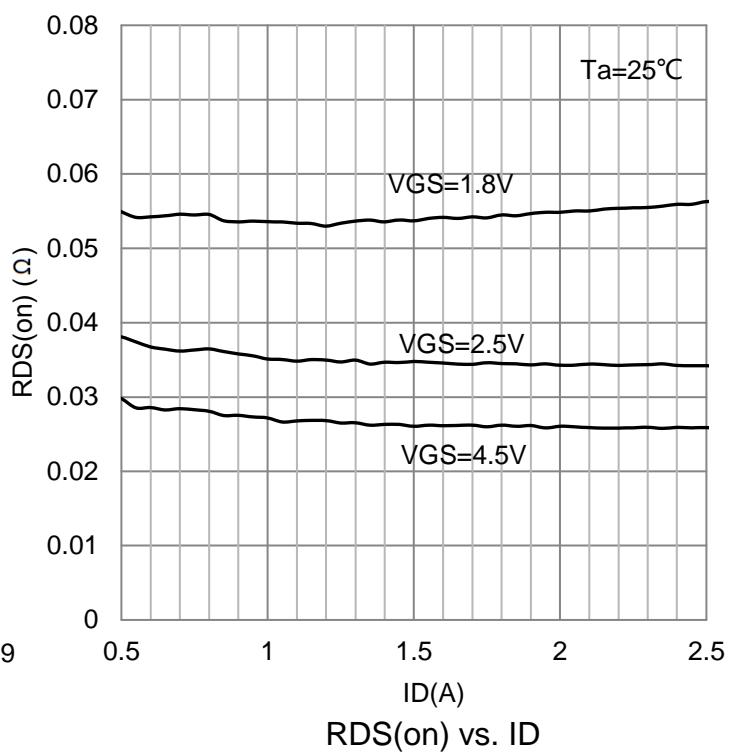
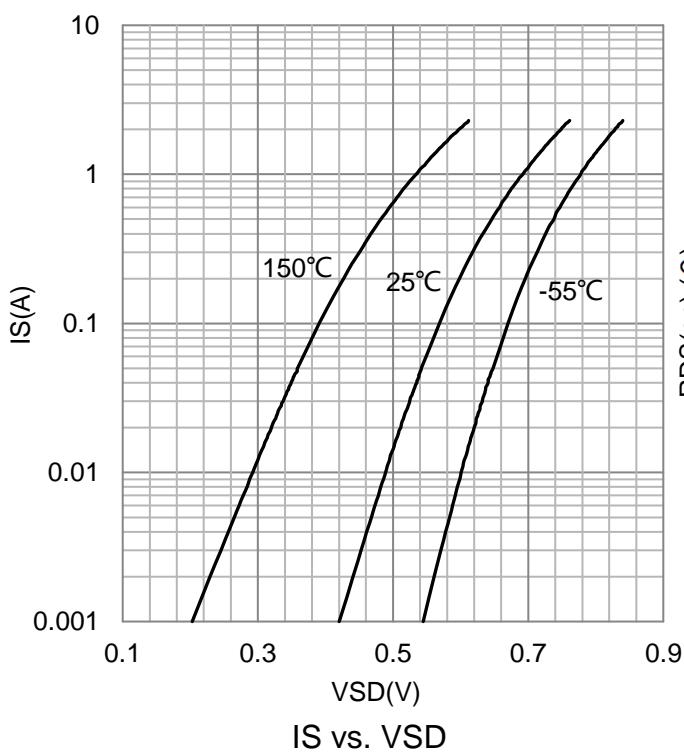
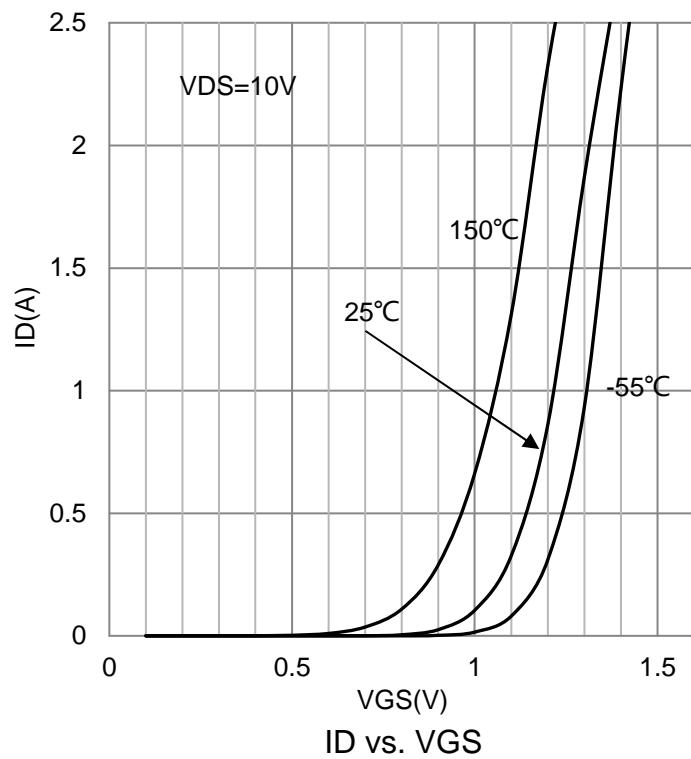
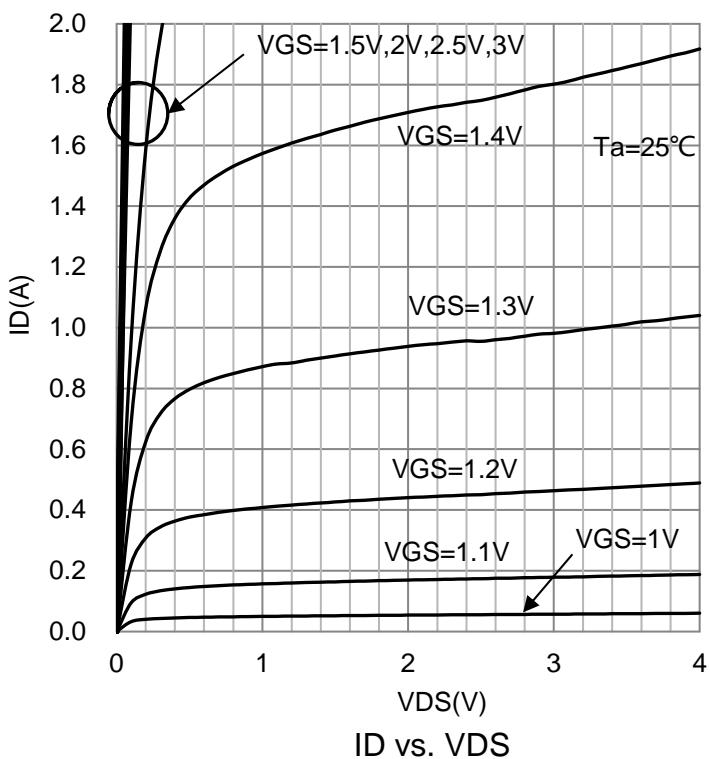
Parameter	Symbol	Min.	Typ.	Max.	Unit
<b>Static</b>					
Drain-Source Breakdown Voltage (VGS = 0 V ID = 250 μA)	BVDSS	20	-	-	V
Drain-Source On-State Resistance (VGS= 4.5 V, ID = 1 A) (VGS= 2.5 V, ID = 1 A) (VGS= 1.8 V, ID = 1 A)	RDS(on)	-	-	60	mΩ
		-	-	75	
		-	-	100	
Gate Threshold Voltage (VDS = VGS, ID = 250 uA)	VGS(th)	0.4	-	1.2	V
Zero Gate Voltage Drain Current (VDS = 20 V, VGS = 0 V)	IDSS	-	-	1	uA
Gate Body Leakage (VGS = ± 12 V, VDS = 0 V)	IGSS	-	-	±1	uA
Diode Forward Voltage (IS = 1 A, VGS = 0 V)	VSD	-	-	1.5	V
<b>Dynamic</b>					
Input Capacitance	(VDS = 8 V, VGS = 0 V, f= 1MHz)	Ciss	-	565	pF
Output Capacitance		Coss	-	105	
Reverse Transfer Capacitance		Crss	-	75	
Total Gate Charge	(VDS = 10 V, ID = 6 A, VGS = 4.5 V)	Qg	-	5	nC
Gate-Source Charge		Qgs	-	1	
Gate-Drain Charge		Qgd	-	1.5	
Turn-On Delay Time	(VDD =10 V,RG = 6Ω ,ID = 1 A, VGS = 4.5 V)	td(on)	-	8	nS
Turn-On Rise Time		tr	-	10	
Turn-Off Delay Time		td(off)	-	22	
Turn-Off Fall Time		tf	-	6	

## 5. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

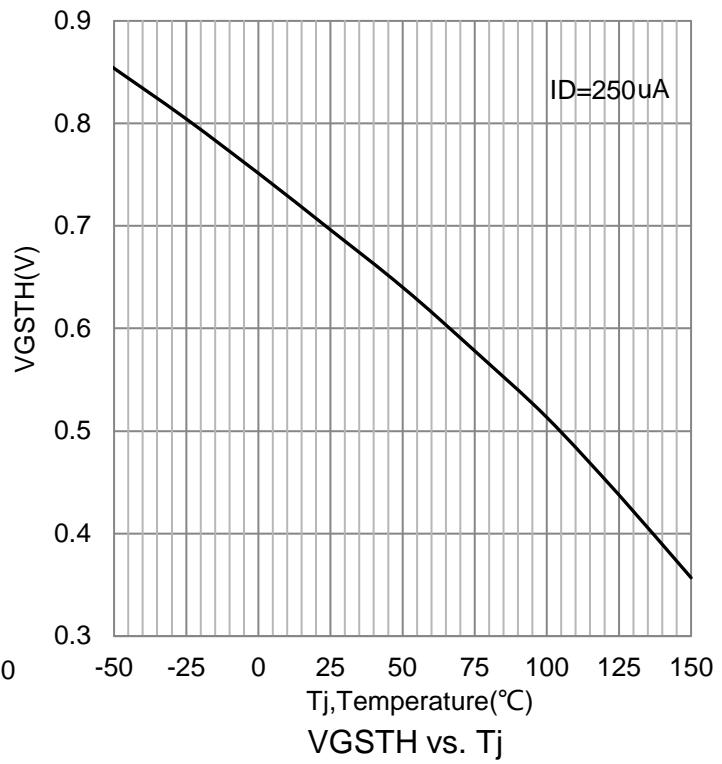
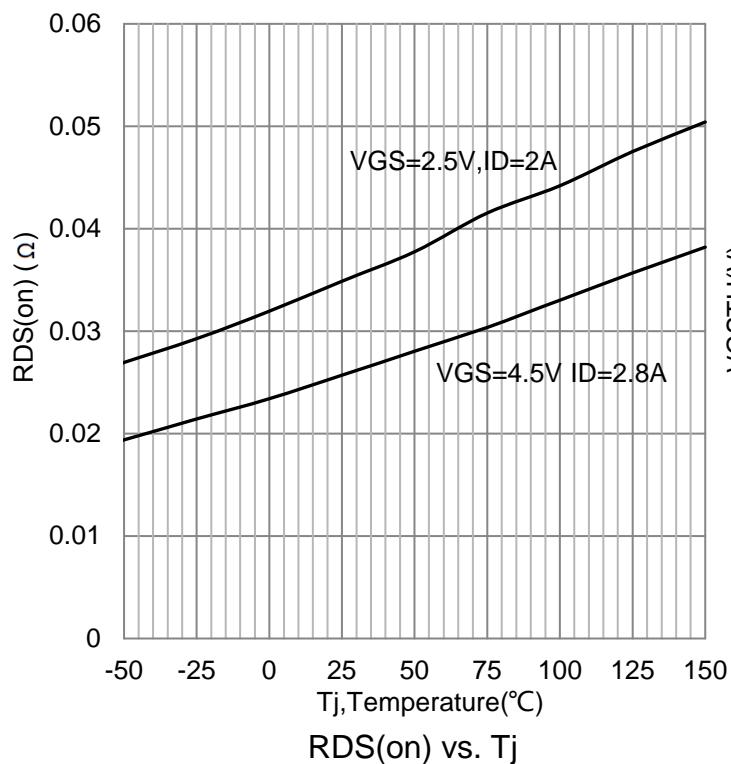
### P-Channel

Parameter	Symbol	Min.	Typ.	Max.	Unit
<b>Static</b>					
Drain-Source Breakdown Voltage (VGS = 0 V ID = -250 µA)	BVDSS	-20	-	-	V
Drain-Source On-State Resistance (VGS= -4.5 V, ID = -1 A) (VGS= -2.5 V, ID = -1 A) (VGS= -1.8 V, ID = -1 A)	RDS(on)	-	-	80	mΩ
		-	-	95	
		-	-	120	
Gate Threshold Voltage (VDS = VGS, ID = -250 uA)	VGS(th)	-0.4	-	-1	V
Zero Gate Voltage Drain Current (VDS = -20 V, VGS = 0 V)	IDSS	-	-	-1	uA
Gate Body Leakage (VGS = ± 8 V, VDS = 0 V)	IGSS	-	-	±1	uA
Diode Forward Voltage (IS = -1 A, VGS = 0 V)	VSD	-	-	-1.5	V
<b>Dynamic</b>					
Input Capacitance	(VDS = -4 V, VGS = 0 V, f= 1MHz)	Ciss	-	1245	pF
Output Capacitance		Coss	-	375	
Reverse Transfer Capacitance		Crss	-	210	
Total Gate Charge	(VDS = -6 V, ID = -2.8 A, VGS = -4.5 V)	Qg	-	9.1	nC
Gate-Source Charge		Qgs	-	2	
Gate-Drain Charge		Qgd	-	1.7	
Turn-On Delay Time	(VDD = -4 V,RL = 4Ω ,ID = -1 A, VGS = -4.5 V, RG = 6 Ω)	td(on)	-	13	nS
Turn-On Rise Time		tr	-	25	
Turn-Off Delay Time		td(off)	-	55	
Turn-Off Fall Time		tf	-	19	

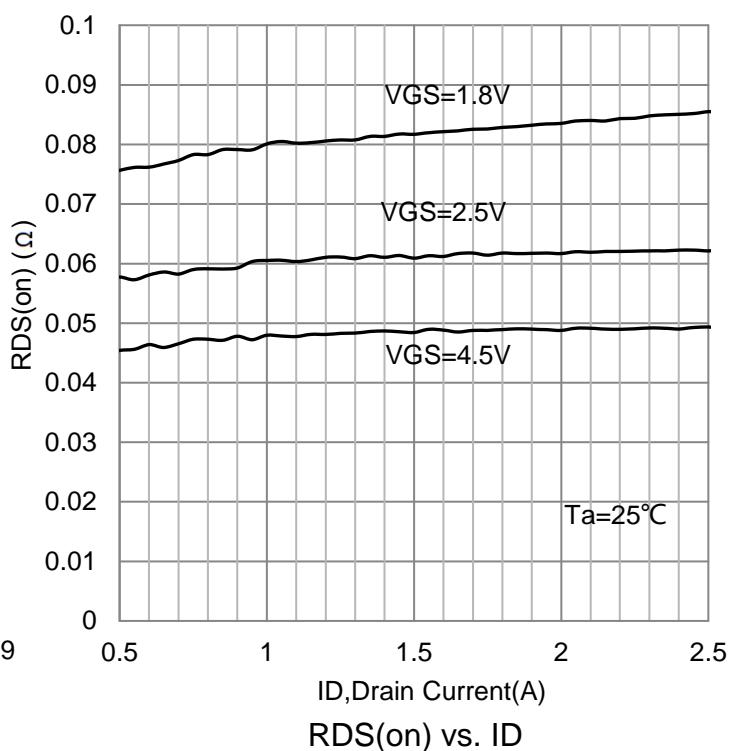
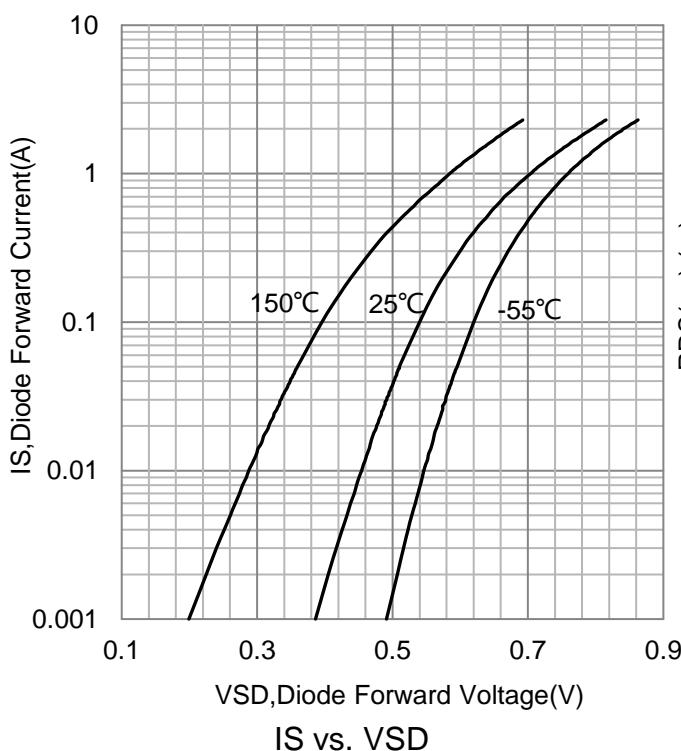
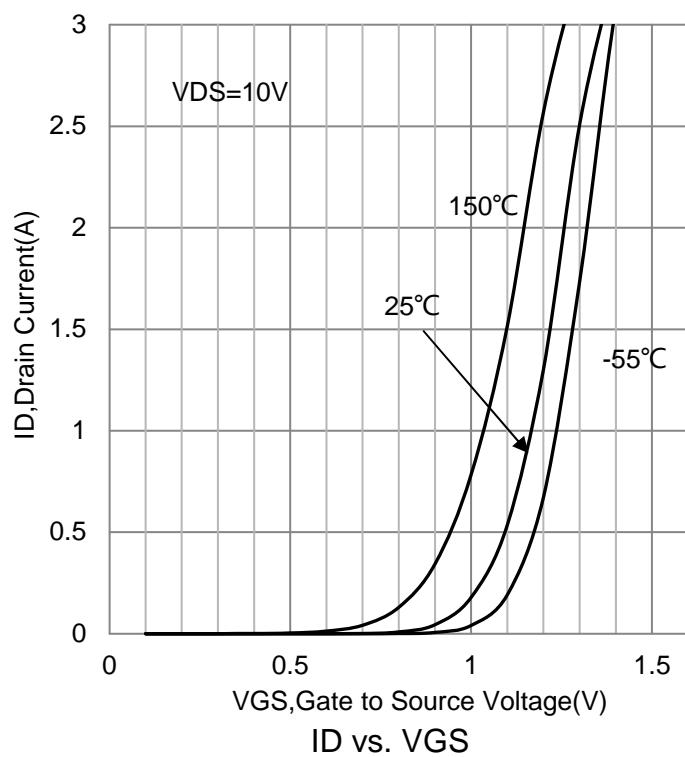
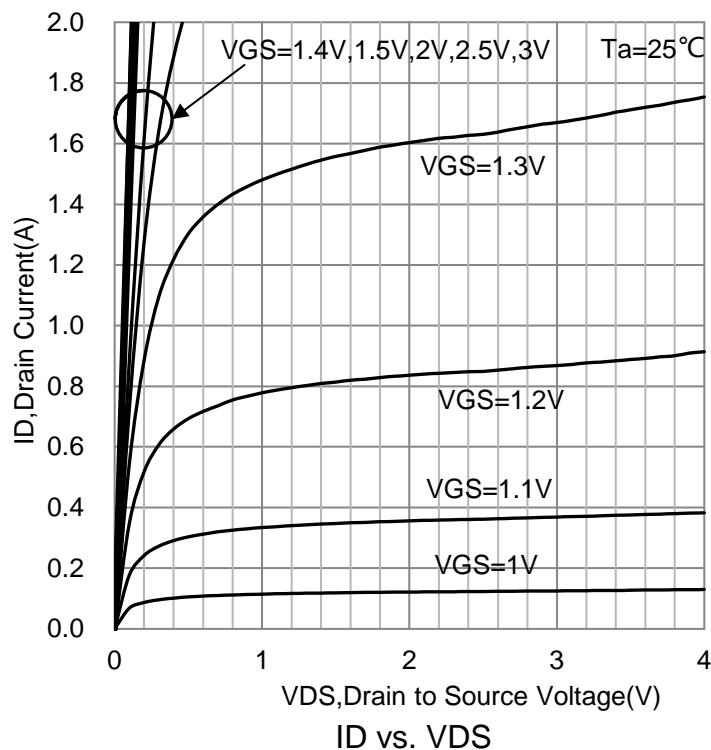
## 6.ELECTRICAL CHARACTERISTICS CURVES(N-Channel)



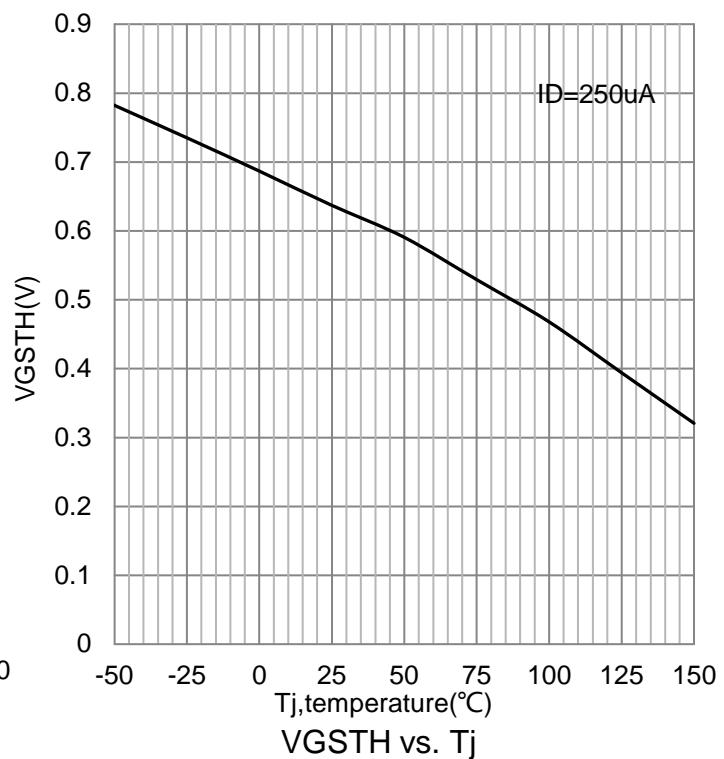
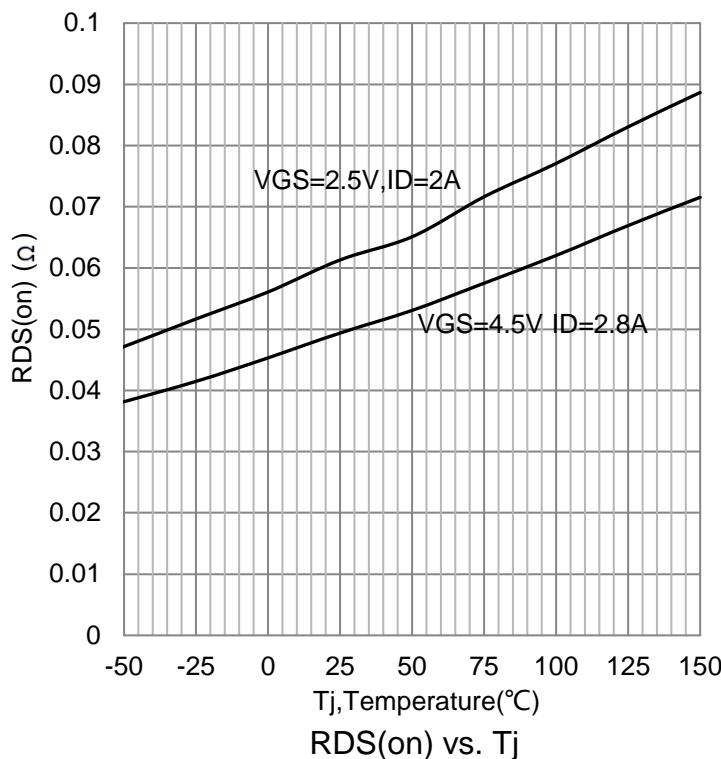
## 6.ELECTRICAL CHARACTERISTICS CURVES(N-Channel)(Con.)



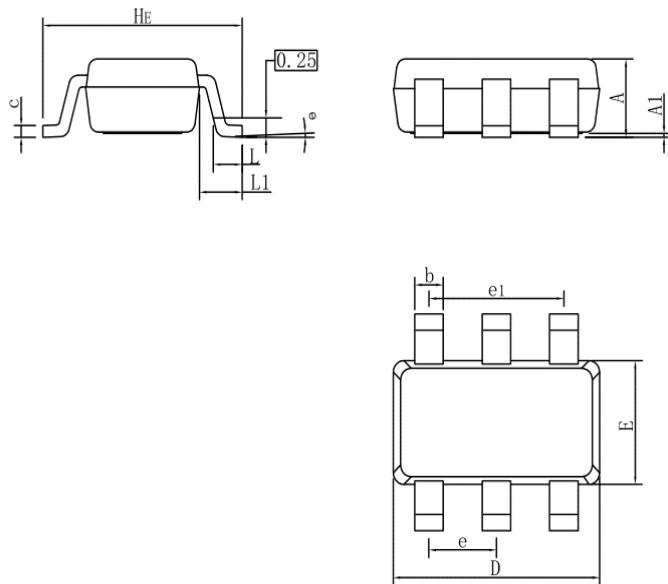
## 6.ELECTRICAL CHARACTERISTICS CURVES(P-Channel)



## 6.ELECTRICAL CHARACTERISTICS CURVES(P-Channel)(Con.)

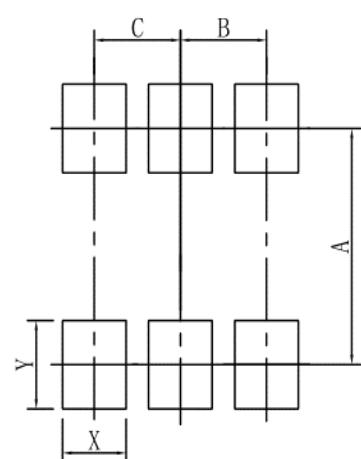


## 7. OUTLINE AND DIMENSIONS



SOT26			
DIM	MIN	NOR	MAX
A	0.90	1.00	1.10
A1	0.01	0.06	0.10
b	0.30	0.40	0.50
c	0.10	0.17	0.20
D	2.80	2.90	3.00
E	1.50	1.60	1.70
e	0.85	0.95	1.05
e1	1.80	1.90	2.00
L	0.20	0.40	0.60
L1	0.60REF		
HE	2.60	2.80	3.00
θ	0 °	-	10 °

## 8. SOLDERING FOOTPRINT



SOT26	
DIM	(mm)
X	0.70
Y	0.90
A	2.40
B	0.95
C	0.95

## DISCLAIMER

- Curve guarantee in the specification. The curve of test items with electric parameter is used as quality guarantee.  
The curve of test items without electric parameter is used as reference only.
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